

FTDI Chip End of Life Policy

FTDI Chip develops innovative silicon solutions that enhance interaction with the latest in global technology. The major objective from the company is to 'bridge technologies' in order to support engineers with highly sophisticated, feature-rich, robust and simple-to-use product platforms. These platforms enable creation of electronic designs with high performance, few peripheral component requirements, low power budgets and minimal board real estate.

A key requirement to taking advantage of this strategy is the company commitment to ensuring continued supply of compatible products over a sustained period of time. By targeting and growing substantial 'long-term' business, FTDI Chip considers this requirement a key aspect of the company strategy.

There are two main threats to the long term provision of FTDI Chip Integrated Circuit (IC) solutions:

1. Sales of the IC device drop to such a low volume that the device becomes unsustainable;
2. The silicon technology in which the IC is fabricated is made obsolete by the semiconductor foundry.

The first point depends largely on the device and the type of application. As a large part of FTDI Chip's target market is those developing long term products, this is considered a low level threat. Many customer applications have volumes which are relatively small; however there are a large number of these applications and cumulatively they contribute to a considerably long term business.

With respect to the second point, there is no doubt that the continued advance in silicon technology will eventually obsolete the process in which these devices are currently manufactured. This problem is the same for any supplier of integrated circuits. In order to take advantage of the substantial and long term nature of the market for which these products have been designed, FTDI Chip will consider developing compatible replacements for these products. This decision will be determined by market requirements.

Last Time buy process

FTDI Chip currently observes the following last time buy process as standard procedure for all products.

Notice of Obsolescence

FTDI Chip will inform its customers of the decision to make any device obsolete. This notice will be sent directly to existing customers and will also be available via the company website and via customer mailer.

The Notice of Obsolescence will include the following:-

1. Date at which the End of Life (EOL) process begins.
2. Recommendation of a replacement for the obsoleted part where applicable.
3. Availability of documentation and samples for the replacement part where applicable.
4. A clear statement concerning the revision markings on both the obsoleted and the replacement devices.



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Final Order Period

FTDI Chip will identify the period, from the start of the last time buy process, during which further orders of the device will be accepted. Our standard Final Order Period is 120 days.

Final Delivery Period

FTDI Chip will identify the period, immediately after the end of the Final Order Period, during which customers may take delivery of their final orders. This notice will include a final date after which no shipment will be made. The standard Final Delivery Period will be 120 days.

On behalf of Future Technology Devices International Ltd,

A handwritten signature in black ink that reads 'Fred Dart.' with a period at the end.

Fred Dart, Managing Director Future Technology Devices International Ltd.
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Revision History

Version 1.0	First Release	29 th May 2009
Version 1.1	Update to policy wording to include all FTDI Product Lines (USB, Display, MCU)	15 th May 2015